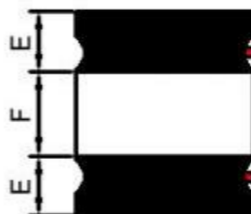
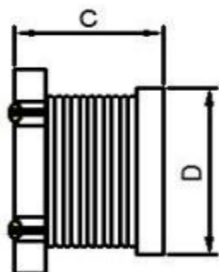
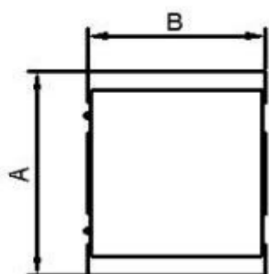


SMD Power Inductors
◆ Dimensions(Unit:mm):


A	5.7±0.3
B	5.0±0.3
C	4.7±0.3
D	5.0±0.3
E	2.1±0.2
F	1.5±0.2

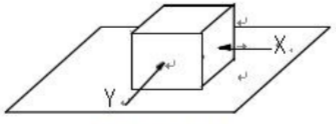
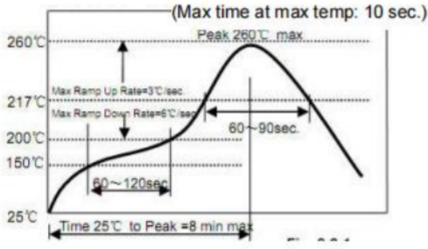
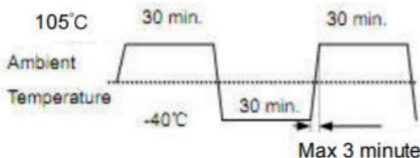
◆ Electrical Characteristics:

Part No	Inductance 1MHz/0.25V	Tolerance	DCR	IDC	S.R.F
			±40%	MAX	Min
Units	uH	±%	Ω	A	MHz
SCN5750NR27MST	0.27	20	0.01	5.3	300
SCN5750NR47MST	0.47	20	0.013	4.8	200
SCN5750N1R0MST	1.0	20	0.019	4.0	150
SCN5750N1R5MST	1.5	20	0.022	3.7	110
SCN5750N2R2MST	2.2	20	0.029	3.2	80
SCN5750N3R3MST	3.3	20	0.036	2.9	40
SCN5750N4R7MST	4.7	20	0.041	2.7	30
SCN5750N6R8MST	6.8	20	0.074	2.0	25
SCN5750N100MST	10.0	20	0.093	1.7	20
SCN5750N150MST	15.0	20	0.150	1.4	17
SCN5750N220MST	22.0	20	0.190	1.2	15
SCN5750N330MST	33.0	20	0.320	0.9	12
SCN5750N470MST	47.0	20	0.400	0.8	10
SCN5750N680MST	68.0	20	0.670	0.64	7.6
SCN5750N101MST	100	20	0.860	0.56	6.5
SCN5750N151MST	150	20	1.90	0.42	5.0
SCN5750N221MST	220	20	2.40	0.32	4.0
SCN5750N331MST	330	20	4.40	0.27	3.1

※1 : All test data is referenced to 25°C ambient;

※2 : This indicates the value of current when the inductance is 10% lower than its initial value at D.C superposition and D.C current when temperature rise ΔT=40°C.(Ta=25°C)

◆ Reliability Test

Items	Requirements	Test Method/Condition
Terminal Strength	No removal or split of the termination or other defects shall occur  Fig.7.1-1	1.Solder the inductor to the testing jig (glass epoxy board shown in Fig.7.1-1) using eutectic solder. Then apply a force in the direction of the arrow. 2.10N force 3.Keep time: 5±2s
High Temperature	1.No visible mechanical damage 2.Inductance change: Within ±10%.	1.Storage Temperature :125±5℃ 2.Duration : 96 ±4 Hours 3.Recovery : then measured at room ambient temperature after placing 24 hours.
Low Temperature	1.No visible mechanical damage 2.Inductance change: Within ±10%	1.Temperature and time: -40±5℃ 2.Duration: 96 ±4 hours 3.Recovery : then measured at room ambient temperature after placing 24 hours
Vibration test	1.No visible mechanical damage 2.Inductance change: Within ±10%	1.Frequency range:10Hz~55Hz~10Hz 2.Amplitude:1.5mm p-p 3.Direction:X,Y,Z 4.Time:1 minute/cycle,2hours per axis
High Temperature Storage Tested	1.No visible mechanical damage. 2.Inductance change: Within ±10%	1.Storage Temperature :60±2℃ 2.Relative Humidity :90-95% RH 3.Duration : 96 ±4 Hours 4.Recovery : then measured at room ambient temperature after placing 24 hours
Resistance to Soldering Heat	1.No visible mechanical damage 2.Inductance change: Within ±10%  Fig.7.6-1	1.Re-flowing Profile: Please refer to Fig.7.6-1 2.Test board thickness: 1.0mm 3.Test board material: glass epoxy resin 4.The chip shall be stabilized at normal condition for 1~2 hours before measuring
Thermal Shock	1.No visible mechanical damage. 2.Inductance change: Within ±10%  Fig.7.7-1	1.Temperature and time: -40±3℃ for 30±3 min→ 105℃ for 30±3min, please refer to Fig.7.7 -1 2.Transforming interval: Max,3 minute 3.Tested cycle: 100 cycles 4.The chip shall be stabilized at normal condition for 1~2 hours before measuring